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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	96
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-75t144i

Product Term Allocator

The product term allocator assigns product terms from a cluster to either logic or control applications as required by the design being implemented. Product terms that are used as logic are steered into a 5-input OR gate associated with the cluster. Product terms that used for control are steered either to the macrocell or I/O cell associated with the cluster. Table 3 shows the available functions for each of the five product terms in the cluster. The OR gate output connects to the associated I/O cell, providing a fast path for narrow combinatorial functions, and to the logic allocator.

Table 3. Individual PT Steering

Product Term	Logic	Control
PT n	Logic PT	Single PT for XOR/OR
PT $n+1$	Logic PT	Individual Clock (PT Clock)
PT $n+2$	Logic PT	Individual Initialization or Individual Clock Enable (PT Initialization/CE)
PT $n+3$	Logic PT	Individual Initialization (PT Initialization)
PT $n+4$	Logic PT	Individual OE (PTOE)

Cluster Allocator

The cluster allocator allows clusters to be steered to neighboring macrocells, thus allowing the creation of functions with more product terms. Table 4 shows which clusters can be steered to which macrocells. Used in this manner, the cluster allocator can be used to form functions of up to 20 product terms. Additionally, the cluster allocator accepts inputs from the wide steering logic. Using these inputs, functions up to 80 product terms can be created.

Table 4. Available Clusters for Each Macrocell

Macrocell	Available Clusters			
M0	—	C0	C1	C2
M1	C0	C1	C2	C3
M2	C1	C2	C3	C4
M3	C2	C3	C4	C5
M4	C3	C4	C5	C6
M5	C4	C5	C6	C7
M6	C5	C6	C7	C8
M7	C6	C7	C8	C9
M8	C7	C8	C9	C10
M9	C8	C9	C10	C11
M10	C9	C10	C11	C12
M11	C10	C11	C12	C13
M12	C11	C12	C13	C14
M13	C12	C13	C14	C15
M14	C13	C14	C15	—
M15	C14	C15	—	—

Wide Steering Logic

The wide steering logic allows the output of the cluster allocator n to be connected to the input of the cluster allocator $n+4$. Thus, cluster chains can be formed with up to 80 product terms, supporting wide product term functions and allowing performance to be increased through a single GLB implementation. Table 5 shows the product term chains.

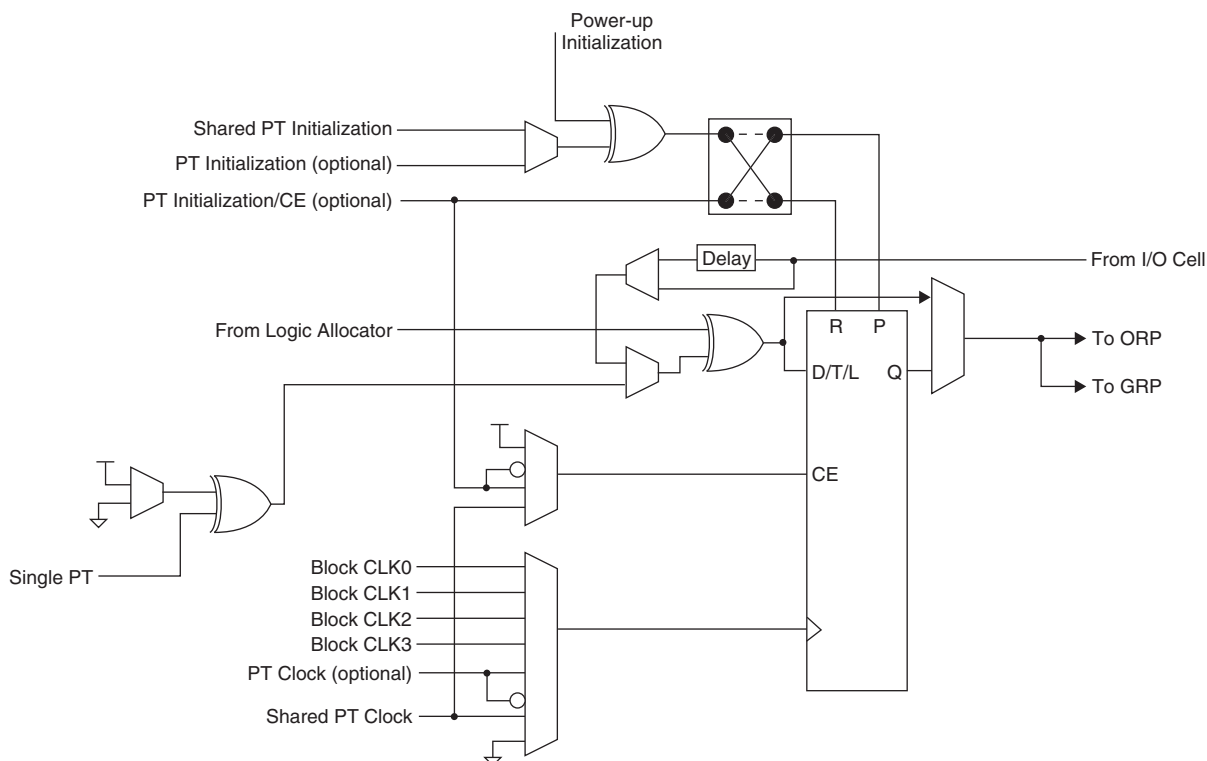
Table 5. Product Term Expansion Capability

Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of t_{EXP} . When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

Macrocell

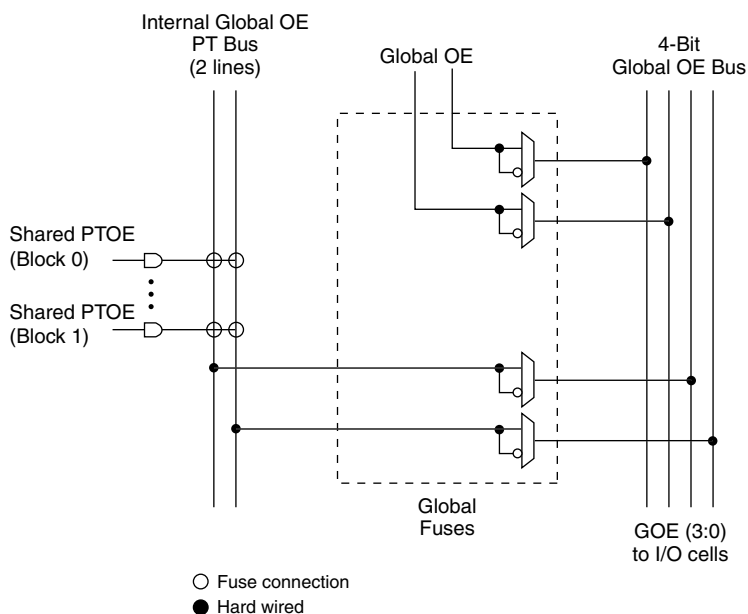
The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

Figure 5. Macrocell

Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1

Figure 10. Global OE Generation for ispMACH 4032

Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E^2 low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice’s ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

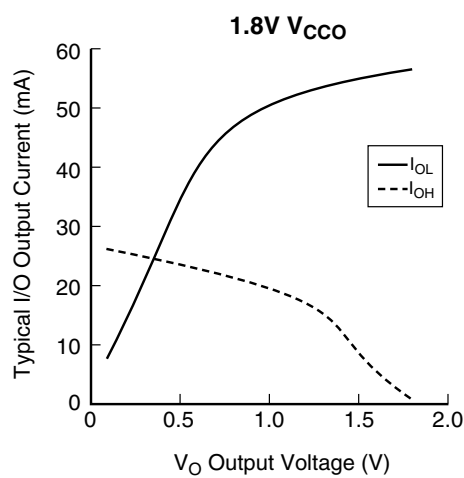
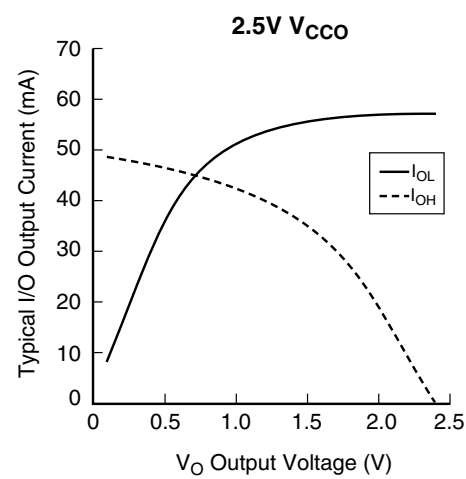
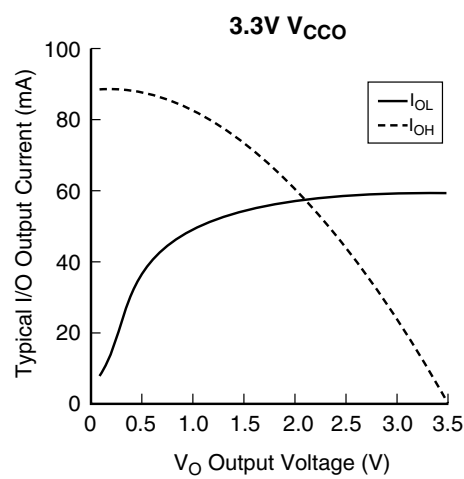
Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}^{4}	Standby Power Supply Current	$V_{CC} = 3.3V$	—	13	—	mA
		$V_{CC} = 2.5V$	—	13	—	mA
		$V_{CC} = 1.8V$	—	3	—	mA

1. $T_A = 25^{\circ}C$, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I_{CC} varies with specific device configuration and operating frequency.
4. $T_A = 25^{\circ}C$

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	50	—	μA
		Vcc = 1.9V, T _A = 70°C	—	58	—	μA
		Vcc = 1.9V, T _A = 85°C	—	60	—	μA
		Vcc = 1.9V, T _A = 125°C	—	70	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	10	—	μA
		Vcc = 1.9V, T _A = 70°C	—	13	20	μA
		Vcc = 1.9V, T _A = 85°C	—	15	25	μA
		Vcc = 1.9V, T _A = 125°C	—	22	—	μA
ispMACH 4064ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	80	—	μA
		Vcc = 1.9V, T _A = 70°C	—	89	—	μA
		Vcc = 1.9V, T _A = 85°C	—	92	—	μA
		Vcc = 1.9V, T _A = 125°C	—	109	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	11	—	μA
		Vcc = 1.9V, T _A = 70°C	—	15	25	μA
		Vcc = 1.9V, T _A = 85°C	—	18	35	μA
		Vcc = 1.9V, T _A = 125°C	—	37	—	μA
ispMACH 4128ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	168	—	μA
		Vcc = 1.9V, T _A = 70°C	—	190	—	μA
		Vcc = 1.9V, T _A = 85°C	—	195	—	μA
		Vcc = 1.9V, T _A = 125°C	—	212	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	12	—	μA
		Vcc = 1.9V, T _A = 70°C	—	16	35	μA
		Vcc = 1.9V, T _A = 85°C	—	19	50	μA
		Vcc = 1.9V, T _A = 125°C	—	42	—	μA



ispMACH 4000Z External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	3.5	—	3.7	—	4.2	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	4.4	—	4.7	—	5.7	ns
t _S	GLB register setup time before clock	2.2	—	2.5	—	2.7	—	ns
t _{ST}	GLB register setup time before clock with T-type register	2.4	—	2.7	—	2.9	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.0	—	1.1	—	1.3	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.0	—	2.1	—	2.6	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.0	—	3.2	—	3.5	ns
t _R	External reset pin to output delay	—	5.0	—	6.0	—	7.3	ns
t _{RW}	External reset pulse duration	1.5	—	1.7	—	2.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	7.0	—	8.0	—	8.0	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	6.5	—	7.0	—	8.0	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	4.5	—	4.5	—	4.8	ns
t _{CW}	Global clock width, high or low	1.0	—	1.5	—	1.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.0	—	1.5	—	1.8	—	ns
t _{WIR}	Input register clock width, high or low	1.0	—	1.5	—	1.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	267	—	250	—	220	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	192	—	175	—	161	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-2.5		-2.7		-3		-3.5		Units
t_{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	0.28	—	ns
t_{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	1.67	—	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	1.12	—	1.12	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	—	0.87	ns
t_{BSR}	Block PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.11	—	1.41	—	1.51	—	1.61	ns
t_{GPTOE}	Global PT OE Delay	—	2.83	—	4.13	—	5.33	—	5.33	ns
t_{PTOE}	Macrocell PT OE Delay	—	1.83	—	2.13	—	2.33	—	2.83	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.75	—	0.80	—	0.75	ns
t _{GOE}	Global OE Pin Delay	—	2.25	—	2.25	—	2.30	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.60	—	1.60	—	1.95	ns
t _{BUF}	Delay through Output Buffer	—	0.75	—	0.90	—	0.90	ns
t _{EN}	Output Enable Time	—	2.25	—	2.25	—	2.50	ns
t _{DIS}	Output Disable Time	—	1.35	—	1.35	—	2.50	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	1.60	—	1.60	—	2.15	ns
t _{MCELL}	Macrocell Delay	—	0.65	—	0.75	—	0.85	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.91	—	1.00	—	1.00	ns
t _{FBK}	Internal Feedback Delay	—	0.05	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.40	—	0.40	—	0.40	ns
t _{PDi}	Macrocell Propagation Delay	—	0.25	—	0.25	—	0.65	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.35	—	1.95	—	1.90	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.00	—	1.15	—	1.10	—	ns
t _{ST_PT}	T-register Setup Time (Product Term Clock)	1.55	—	1.75	—	2.10	—	ns
t _H	D-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
t _{HT}	T-Resister Hold Time	1.40	—	1.55	—	1.80	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	0.94	—	0.90	—	1.50	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	1.06	—	1.20	—	1.10	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.88	—	1.00	—	1.00	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.65	—	0.70	—	0.65	ns
t _{CES}	Clock Enable Setup Time	1.00	—	2.00	—	2.00	—	ns
t _{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t _{SL}	Latch Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.55	—	1.95	—	1.90	—	ns
t _{HL}	Latch Hold Time	1.40	—	1.80	—	1.80	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.40	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.30	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.28	—	0.28	—	1.27	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	2.00	—	1.67	—	1.80	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.30	—	1.50	—	1.55	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	1.50	—	1.70	—	1.55	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.10	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	1.22	—	2.02	—	1.83	ns

ispMACH 4000V/B/C Timing Adders¹ (Cont.)

Adder Type	Base Parameter	Description	-5		-75		-10		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.00	—	1.00	—	1.00	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	ns
t _{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	ns
t _{BLA}	t _{ROUTE}	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters									
LVTTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters									
LVTTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

ispMACH 4000Z Timing Adders (Cont.)¹

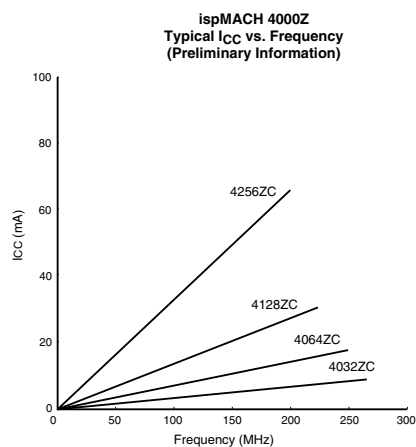
Adder Type	Base Parameter	Description	-45		-5		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.30	—	1.30	—	1.30	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.45	—	0.45	—	0.50	ns
t _{ORP}	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t _{BLA}	t _{ROUTE}	Additional block load-ing adder	—	0.05	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters									
LVTTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters									
LVTTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

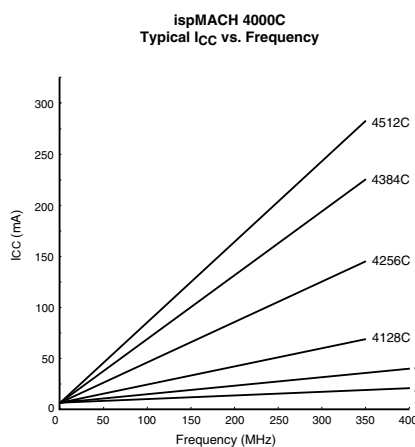
Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

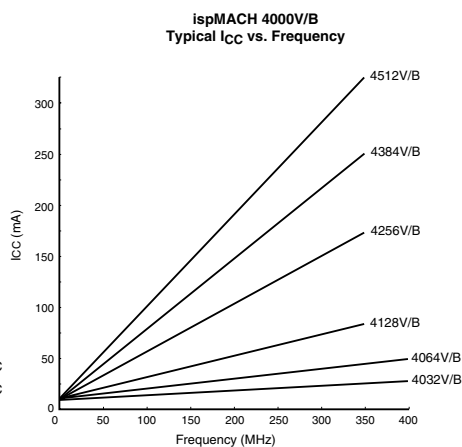
Power Consumption



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 3.3V, 2.5V, 25°C.

Power Estimation Coefficients¹

Device	A	B
ispMACH 4032V/B	11.3	0.010
ispMACH 4032C	1.3	0.010
ispMACH 4064V/B	11.5	0.010
ispMACH 4064C	1.5	0.010
ispMACH 4128V/B	11.5	0.011
ispMACH 4128C	1.5	0.011
ispMACH 4256V/B	12	0.011
ispMACH 4256C	2	0.011
ispMACH 4384V/B	12.5	0.013
ispMACH 4384C	2.5	0.013
ispMACH 4512V/B	13	0.013
ispMACH 4512C	3	0.013
ispMACH 4032ZC	0.010	0.010
ispMACH 4064ZC	0.011	0.010
ispMACH 4128ZC	0.012	0.010
ispMACH 4256ZC	0.013	0.010

1. For further information about the use of these coefficients, refer to TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#).

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CCO0} , V _{CCO1}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB		4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB		8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹

Signal	44-pin TQFP ²	48-pin TQFP ²	56-ball csBGA ³	100-pin TQFP ²	128-pin TQFP ²
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	4032Z: A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.
2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A ⁵	A10	A ⁵
3	0	A6	A ⁶	A12	A ⁶
4	0	A7	A ⁷	A14	A ⁷
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A ⁸	B0	B ⁰
8	0	A9	A ⁹	B2	B ¹
9	0	A10	A ¹⁰	B4	B ²
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A ¹²	B8	B ⁴
14	0	A13	A ¹³	B10	B ⁵
15	0	A14	A ¹⁴	B12	B ⁶
16	0	A15	A ¹⁵	B14	B ⁷
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B ⁰	C0	C ⁰
19	1	B1	B ¹	C2	C ¹
20	1	B2	B ²	C4	C ²
21	1	B3	B ³	C6	C ³
22	1	B4	B ⁴	C8	C ⁴
23	-	TMS	-	TMS	-
24	1	B5	B ⁵	C10	C ⁵
25	1	B6	B ⁶	C12	C ⁶
26	1	B7	B ⁷	C14	C ⁷
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B ⁸	D0	D ⁰
30	1	B9	B ⁹	D2	D ¹
31	1	B10	B ¹⁰	D4	D ²
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B ¹²	D8	D ⁴
36	1	B13	B ¹³	D10	D ⁵
37	1	B14	B ¹⁴	D12	D ⁶
38	1	B15/GOE1	B ¹⁵	D14/GOE1	D ⁷
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
41	0	A1	A ¹	A2	A ¹

ispMACH 4032Z and 4064Z Logic Signal Connections: 56-Ball csBGA (Cont.)

Ball Number	Bank Number	ispMACH 4032Z		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
K5	0	A15	A ¹⁵	B0	B ⁰
H6	0	CLK1/I	-	CLK1/I	-
K6	1	CLK2/I	-	CLK2/I	-
H7	1	B0	B ⁰	C0	C ⁰
K7	1	B1	B ¹	C1	C ¹
K8	1	B2	B ²	C2	C ²
K9	1	B3	B ³	C4	C ³
K10	1	B4	B ⁴	C6	C ⁴
J10	-	TMS	-	TMS	-
H8	1	B5	B ⁵	C8	C ⁵
H10	1	B6	B ⁶	C10	C ⁶
G10	1	B7	B ⁷	C11	C ⁷
G8	1	GND (Bank 1)	-	GND (Bank 1)	-
F8	1	NC ¹	-	I ¹	-
F10	1	NC ¹	-	I ¹	-
E8	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
E10	1	B8	B ⁸	D15	D ⁷
D8	1	B9	B ⁹	D12	D ⁶
D10	1	B10	B ¹⁰	D10	D ⁵
C10	1	B11	B ¹¹	D8	D ⁴
B10	1	NC ¹	-	I ¹	-
A10	-	TDO	-	TDO	-
A9	-	VCC	-	VCC	-
C8	-	GND	-	GND	-
A8	1	NC ¹	-	I ¹	-
A7	1	B12	B ¹²	D6	D ³
C7	1	B13	B ¹³	D4	D ²
C6	1	B14	B ¹⁴	D2	D ¹
A6	1	B15/GOE1	B ¹⁵	D0/GOE1	D ⁰
C5	1	CLK3/I	-	CLK3/I	-
A5	0	CLK0/I	-	CLK0/I	-
C4	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
A4	0	A1	A ¹	A1	A ¹
A3	0	A2	A ²	A2	A ²
A2	0	A3	A ³	A4	A ³
A1	0	A4	A ⁴	A6	A ⁴

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4064Z devices.

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H ⁴	L8	L ⁴	P8	P ⁴
61	0	H6	H ³	L6	L ³	P6	P ³
62	0	H4	H ²	L4	L ²	P4	P ²
63	0	H2	H ¹	L2	L ¹	P2	P ¹
64	0	H0	H ⁰	L0	L ⁰	P0	P ⁰
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I ⁰	M0	M ⁰	AX0	AX ⁰
71	1	I2	I ¹	M2	M ¹	AX2	AX ¹
72	1	I4	I ²	M4	M ²	AX4	AX ²
73	1	I6	I ³	M6	M ³	AX6	AX ³
74	1	I8	I ⁴	M8	M ⁴	AX8	AX ⁴
75	1	I10	I ⁵	M10	M ⁵	AX10	AX ⁵
76	1	I12	I ⁶	M12	M ⁶	AX12	AX ⁶
77	1	I14	I ⁷	M14	M ⁷	AX14	AX ⁷
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J ⁰	N0	N ⁰	BX0	BX ⁰
81	1	J2	J ¹	N2	N ¹	BX2	BX ¹
82	1	J4	J ²	N4	N ²	BX4	BX ²
83	1	J6	J ³	N6	N ³	BX6	BX ³
84	1	J8	J ⁴	N8	N ⁴	BX8	BX ⁴
85	1	J10	J ⁵	N10	N ⁵	BX10	BX ⁵
86	1	J12	J ⁶	N12	N ⁶	BX12	BX ⁶
87	1	J14	J ⁷	N14	N ⁷	BX14	BX ⁷
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K ⁷	O14	O ⁷	CX14	CX ⁷
94	1	K12	K ⁶	O12	O ⁶	CX12	CX ⁶
95	1	K10	K ⁵	O10	O ⁵	CX10	CX ⁵
96	1	K8	K ⁴	O8	O ⁴	CX8	CX ⁴
97	1	K6	K ³	O6	O ³	CX6	CX ³
98	1	K4	K ²	O4	O ²	CX4	CX ²
99	1	K2	K ¹	O2	O ¹	CX2	CX ¹
100	1	K0	K ⁰	O0	O ⁰	CX0	CX ⁰

ispMACH 4000C (1.8V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384C	LC4384C-5FT256I	384	1.8	5	ftBGA	256	192	I
	LC4384C-75FT256I	384	1.8	7.5	ftBGA	256	192	I
	LC4384C-10FT256I	384	1.8	10	ftBGA	256	192	I
	LC4384C-5F256I ¹	384	1.8	5	fpBGA	256	192	I
	LC4384C-75F256I ¹	384	1.8	7.5	fpBGA	256	192	I
	LC4384C-10F256I ¹	384	1.8	10	fpBGA	256	192	I
	LC4384C-5T176I	384	1.8	5	TQFP	176	128	I
	LC4384C-75T176I	384	1.8	7.5	TQFP	176	128	I
	LC4384C-10T176I	384	1.8	10	TQFP	176	128	I
LC4512C	LC4512C-5FT256I	512	1.8	5	ftBGA	256	208	I
	LC4512C-75FT256I	512	1.8	7.5	ftBGA	256	208	I
	LC4512C-10FT256I	512	1.8	10	ftBGA	256	208	I
	LC4512C-5F256I ¹	512	1.8	5	fpBGA	256	208	I
	LC4512C-75F256I ¹	512	1.8	7.5	fpBGA	256	208	I
	LC4512C-10F256I ¹	512	1.8	10	fpBGA	256	208	I
	LC4512C-5T176I	512	1.8	5	TQFP	176	128	I
	LC4512C-75T176I	512	1.8	7.5	TQFP	176	128	I
	LC4512C-10T176I	512	1.8	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25T48C	32	2.5	2.5	TQFP	48	32	C
	LC4032B-5T48C	32	2.5	5	TQFP	48	32	C
	LC4032B-75T48C	32	2.5	7.5	TQFP	48	32	C
	LC4032B-25T44C	32	2.5	2.5	TQFP	44	30	C
	LC4032B-5T44C	32	2.5	5	TQFP	44	30	C
	LC4032B-75T44C	32	2.5	7.5	TQFP	44	30	C
LC4064B	LC4064B-25T100C	64	2.5	2.5	TQFP	100	64	C
	LC4064B-5T100C	64	2.5	5	TQFP	100	64	C
	LC4064B-75T100C	64	2.5	7.5	TQFP	100	64	C
	LC4064B-25T48C	64	2.5	2.5	TQFP	48	32	C
	LC4064B-5T48C	64	2.5	5	TQFP	48	32	C
	LC4064B-75T48C	64	2.5	7.5	TQFP	48	32	C
	LC4064B-25T44C	64	2.5	2.5	TQFP	44	30	C
	LC4064B-5T44C	64	2.5	5	TQFP	44	30	C
	LC4064B-75T44C	64	2.5	7.5	TQFP	44	30	C
LC4128B	LC4128B-27T128C	128	2.5	2.7	TQFP	128	92	C
	LC4128B-5T128C	128	2.5	5	TQFP	128	92	C
	LC4128B-75T128C	128	2.5	7.5	TQFP	128	92	C
	LC4128B-27T100C	128	2.5	2.7	TQFP	100	64	C
	LC4128B-5T100C	128	2.5	5	TQFP	100	64	C
	LC4128B-75T100C	128	2.5	7.5	TQFP	100	64	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C ¹	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C ¹	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C ¹	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

ispMACH 4000V (3.3V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5TN48I	32	3.3	5	Lead-free TQFP	48	32	I
	LC4032V-75TN48I	32	3.3	7.5	Lead-free TQFP	48	32	I
	LC4032V-10TN48I	32	3.3	10	Lead-free TQFP	48	32	I
	LC4032V-5TN44I	32	3.3	5	Lead-free TQFP	44	30	I
	LC4032V-75TN44I	32	3.3	7.5	Lead-free TQFP	44	30	I
	LC4032V-10TN44I	32	3.3	10	Lead-free TQFP	44	30	I
LC4064V	LC4064V-5TN100I	64	3.3	5	Lead-free TQFP	100	64	I
	LC4064V-75TN100I	64	3.3	7.5	Lead-free TQFP	100	64	I
	LC4064V-10TN100I	64	3.3	10	Lead-free TQFP	100	64	I
	LC4064V-5TN48I	64	3.3	5	Lead-free TQFP	48	32	I
	LC4064V-75TN48I	64	3.3	7.5	Lead-free TQFP	48	32	I
	LC4064V-10TN48I	64	3.3	10	Lead-free TQFP	48	32	I
	LC4064V-5TN44I	64	3.3	5	Lead-free TQFP	44	30	I
	LC4064V-75TN44I	64	3.3	7.5	Lead-free TQFP	44	30	I
	LC4064V-10TN44I	64	3.3	10	Lead-free TQFP	44	30	I
LC4128V	LC4128V-5TN144I	128	3.3	5	Lead-free TQFP	144	96	I
	LC4128V-75TN144I	128	3.3	7.5	Lead-free TQFP	144	96	I
	LC4128V-10TN144I	128	3.3	10	Lead-free TQFP	144	96	I
	LC4128V-5TN128I	128	3.3	5	Lead-free TQFP	128	92	I
	LC4128V-75TN128I	128	3.3	7.5	Lead-free TQFP	128	92	I
	LC4128V-10TN128I	128	3.3	10	Lead-free TQFP	128	92	I
	LC4128V-5TN100I	128	3.3	5	Lead-free TQFP	100	64	I
	LC4128V-75TN100I	128	3.3	7.5	Lead-free TQFP	100	64	I
	LC4128V-10TN100I	128	3.3	10	Lead-free TQFP	100	64	I

ispMACH 4000V (3.3V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FTN256AI	256	3.3	5	Lead-free ftBGA	256	128	I
	LC4256V-75FTN256AI	256	3.3	7.5	Lead-free ftBGA	256	128	I
	LC4256V-10FTN256AI	256	3.3	10	Lead-free ftBGA	256	128	I
	LC4256V-5FTN256BI	256	3.3	5	Lead-free ftBGA	256	160	I
	LC4256V-75FTN256BI	256	3.3	7.5	Lead-free ftBGA	256	160	I
	LC4256V-10FTN256BI	256	3.3	10	Lead-free ftBGA	256	160	I
	LC4256V-5FN256AI ¹	256	3.3	5	Lead-free fpBGA	256	128	I
	LC4256V-75FN256AI ¹	256	3.3	7.5	Lead-free fpBGA	256	128	I
	LC4256V-10FN256AI ¹	256	3.3	10	Lead-free fpBGA	256	128	I
	LC4256V-5FN256BI ¹	256	3.3	5	Lead-free fpBGA	256	160	I
	LC4256V-75FN256BI ¹	256	3.3	7.5	Lead-free fpBGA	256	160	I
	LC4256V-10FN256BI ¹	256	3.3	10	Lead-free fpBGA	256	160	I
	LC4256V-5TN176I	256	3.3	5	Lead-free TQFP	176	128	I
	LC4256V-75TN176I	256	3.3	7.5	Lead-free TQFP	176	128	I
	LC4256V-10TN176I	256	3.3	10	Lead-free TQFP	176	128	I
	LC4256V-5TN144I	256	3.3	5	Lead-free TQFP	144	96	I
	LC4256V-75TN144I	256	3.3	7.5	Lead-free TQFP	144	96	I
	LC4256V-10TN144I	256	3.3	10	Lead-free TQFP	144	96	I
	LC4256V-5TN100I	256	3.3	5	Lead-free TQFP	100	64	I
	LC4256V-75TN100I	256	3.3	7.5	Lead-free TQFP	100	64	I
	LC4256V-10TN100I	256	3.3	10	Lead-free TQFP	100	64	I
LC4384V	LC4384V-5FTN256I	384	3.3	5	Lead-free ftBGA	256	192	I
	LC4384V-75FTN256I	384	3.3	7.5	Lead-free ftBGA	256	192	I
	LC4384V-10FTN256I	384	3.3	10	Lead-free ftBGA	256	192	I
	LC4384V-5FN256I ¹	384	3.3	5	Lead-free fpBGA	256	192	I
	LC4384V-75FN256I ¹	384	3.3	7.5	Lead-free fpBGA	256	192	I
	LC4384V-10FN256I ¹	384	3.3	10	Lead-free fpBGA	256	192	I
	LC4384V-5TN176I	384	3.3	5	Lead-free TQFP	176	128	I
	LC4384V-75TN176I	384	3.3	7.5	Lead-free TQFP	176	128	I
	LC4384V-10TN176I	384	3.3	10	Lead-free TQFP	176	128	I
LC4512V	LC4512V-5FTN256I	512	3.3	5	Lead-free ftBGA	256	208	I
	LC4512V-75FTN256I	512	3.3	7.5	Lead-free ftBGA	256	208	I
	LC4512V-10FTN256I	512	3.3	10	Lead-free ftBGA	256	208	I
	LC4512V-5FN256I ¹	512	3.3	5	Lead-free fpBGA	256	208	I
	LC4512V-75FN256I ¹	512	3.3	7.5	Lead-free fpBGA	256	208	I
	LC4512V-10FN256I ¹	512	3.3	10	Lead-free fpBGA	256	208	I
	LC4512V-5TN176I	512	3.3	5	Lead-free TQFP	176	128	I
	LC4512V-75TN176I	512	3.3	7.5	Lead-free TQFP	176	128	I
	LC4512V-10TN176I	512	3.3	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.